L Number	Hits	Search Text	DB	Time stamp
1	1	(rta or rapid near2 annealer).ti. and tube	USPAT;	2004/01/09 08:45
		and reactor	US-PGPUB;	
		·	EPO; JPO;	
		·	DERWENT;	
		7.40	IBM_TDB	2004/01/02 02 75
2	220	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 08:51
		and tube and reactor	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
3	302	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 08:51
3	302	near5 (apparatus or housing)	US-PGPUB;	2001, 02, 05 00.31
		(*FF**********************************	EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	282	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 08:51
		near3 (apparatus)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	. <u>-</u>	7.1	IBM_TDB	2004/07/02 27 77
5	42	(rta or rapid near thermal near anneal\$3)	USPAT;	2004/01/09 09:10
		near3 (apparatus) and tube	US-PGPUB;	
			EPO; JPO; DERWENT;	
}			IBM TDB	
6	22	(rta or rapid near thermal near anneal\$3 or	USPAT;	2004/01/09 09:14
"		rtp) same tube same reactor	US-PGPUB;	2001, 01, 05 05:11
		1 sp/ bame base bame readour	EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	29	reactor near2 (slot or opening) same (wafer	USPAT;	2004/01/09 09:16
		or substrate) near5 (position or positioning	US-PGPUB;	
		or positioned or alignment or align or	EPO; JPO;	
		aligning or locating or location)	DERWENT;	
	15010	/	IBM_TDB	2004/01/00 00 45
-	17342	1 '	USPAT;	2004/01/09 08:45
		heat near2 process\$3 or anneal or annealing or annealer) and (position or positioner or	US-PGPUB; EPO; JPO;	
		positioning or aligning or locating or	DERWENT;	
		locator or locater or positioned or	IBM TDB	
		placement or (distance or separation or		İ
		separator) near3 (lamp or heat or source or		
		light)) near5 (wafer or tray or holder or		
		chuck or carrier or substrate)		
-	2066		USPAT;	2004/01/05 14:38
		heat near2 process\$3 or anneal or annealing	US-PGPUB;	
		or annealer) same (position or positioner or	EPO; JPO;	
		positioning or aligning or locating or locator or locater or positioned or	DERWENT; IBM TDB	
		placement or (distance or separation or	1 100,1-100	
		separator) near3 (lamp or heat or source or		
		light)) near5 (wafer or tray or holder or		
		chuck or carrier or substrate)		
-	114	(rta or rtp or thermal near2 process\$3 or	USPAT;	2004/01/05 14:42
		heat near2 process\$3 or anneal or annealing	US-PGPUB;	
		or annealer) same (position or positioner or	EPO; JPO;	
		positioning or aligning or locating or	DERWENT;	
		locator or locater or positioned or	IBM_TDB	
		placement or (distance or separation or	1	
1		separator) near3 (lamp or heat or source or		
		light)) near5 (wafer or tray or holder or chuck or carrier or substrate) near10		
		(groove or notch or c or guide or grooved or		
]		notched)		
·	1			

-	39	(rta or rtp or thermal near2 process\$3 or heat near2 process\$3 or anneal or annealing	USPAT; US-PGPUB;	2004/01/05 15:30
		or annealer) same (position or positioner or positioning or aligning or locating or	EPO; JPO; DERWENT;	
		locator or locater or positioned or	IBM_TDB	
		placement or (distance or separation or	_	
		separator) near3 (lamp or heat or source or light)) near5 (wafer or tray or holder or		
		chuck or carrier or substrate) near10		
		(groove or notch or c near shape\$2 or guide or grooved or notched)		
-	1035		USPAT;	2004/01/05 15:30
			US-PGPUB; EPO; JPO;	
			DERWENT;	
_	114	(rta or rtp or rapid adj thermal).ti. and	IBM_TDB USPAT;	2004/01/06 09:25
		(position or positioning or locating or	US-PGPUB;	
		locator or positioner or groove or guide or distance or spacing) near4 (wafer or	EPO; JPO; DERWENT;	
		substrate or tray or holder or carrier or chuck)	IBM_TDB	
_	4	semiconductor near2 (processing or	USPAT;	2004/01/06 09:28
		fabrication or heating or coating or process) and (substrate or wafer) near2	US-PGPUB; EPO; JPO;	
		(holder or carrier or boat or chuck) near2	DERWENT;	
		(positioner or positioned or aligned or aligner or positioning or placement) near4	IBM_TDB	
	İ	(groove or notch)		
-	24	semiconductor and (substrate or wafer) near2 (holder or carrier or boat or chuck or tray)	USPAT; US-PGPUB;	2004/01/06 09:30
		near2 (positioner or positioned or aligned	EPO; JPO;	
		or aligner or positioning or placement) near8 (groove or notch)	DERWENT; IBM TDB	
-	92	semiconductor and (substrate or wafer) near2	USPAT;	2004/01/06 12:15
		(holder or carrier or boat or chuck or tray) near8 (positioner or positioned or aligned	US-PGPUB; EPO; JPO;	
		or aligner or positioning or placement)	DERWENT;	
-	125	near8 (groove or notch) (substrate or wafer) near10 (holder or	IBM_TDB USPAT;	2004/01/06 12:18
		carrier or boat or chuck or tray) near10	US-PGPUB;	
		(positioner or positioned or aligned or aligner or positioning or placement) near10	EPO; JPO; DERWENT;	
		(discrete or kit or attachable or detachable or separate or nonintegral or non-integral)	IBM_TDB	
-	576	257/E21.324.ccls.	USPAT;	2004/01/06 12:19
			US-PGPUB; EPO; JPO;	
			DERWENT;	
_	78	257/E21.324.ccls. and (wafer or substrate)	IBM_TDB USPAT;	2004/01/06 13:15
	/0	near6 (positioning or position or positioner	US-PGPUB;	
		or positioned or locator or placement or secured or alignment or aligning)	EPO; JPO; DERWENT;	
			IBM_TDB	
1	48	(wafer or substrate) near2 (tray or carrier or holder) near5 (inserting or insertion or	USPAT; US-PGPUB;	2004/01/06 13:25
		insert) near6 (groove or notch or guide or	EPO; JPO;	
		guiding or grooved)	DERWENT; IBM TDB	
-	166	438/663.ccls.	USPAT;	2004/01/06 13:25
			US-PGPUB; EPO; JPO;	
			DERWENT;	
	L		IBM_TDB	

	183	(rta or rtp or anneal or annealer or furnace	USPAT;	2004/01/07 16:35
	103	or diffusion or diffuser or rie or pecvd or	US-PGPUB;	2004/01/07 10.33
		chamber or tube) and (wafer or substrate)	EPO; JPO:	
		, ,	DERWENT;	
		near4 (boat or tray or holder or carrier or chuck) near5 (insertion or insert or	1	
			IBM_TDB	
		inserting or loading or loaded or load)		
		near10 (groove or grooved or track or guide		
		or guided or guiding)		
-	176	`·	USPAT;	2004/01/08 10:11
		or diffusion or diffuser or rie or pecvd or	US-PGPUB;	
		chamber or tube) and (wafer or substrate)	EPO; JPO;	
		near3 (boat or tray or holder or carrier or	DERWENT;	
		chuck) near5 (insertion or insert or	IBM_TDB	
		inserting or loading or loaded or load)		
		near10 (groove or grooved or track or guide		
-		or guided or guiding or notch)		
-	2	5820367.pn.	USPAT;	2004/01/08 10:11
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
_	5	5820367.URPN.	USPAT	2004/01/08 10:11